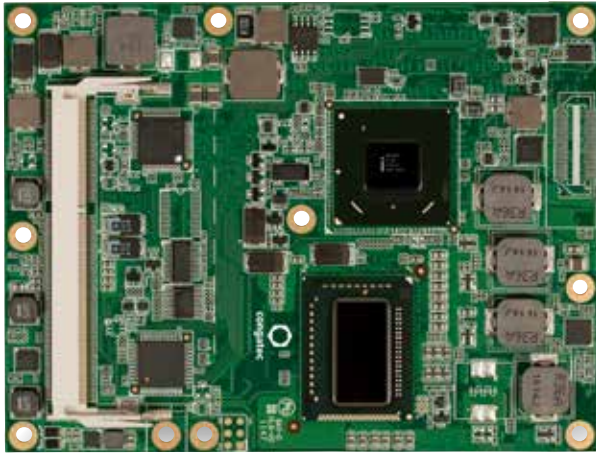


# HIGH PERFORMANCE

# conga-TS67

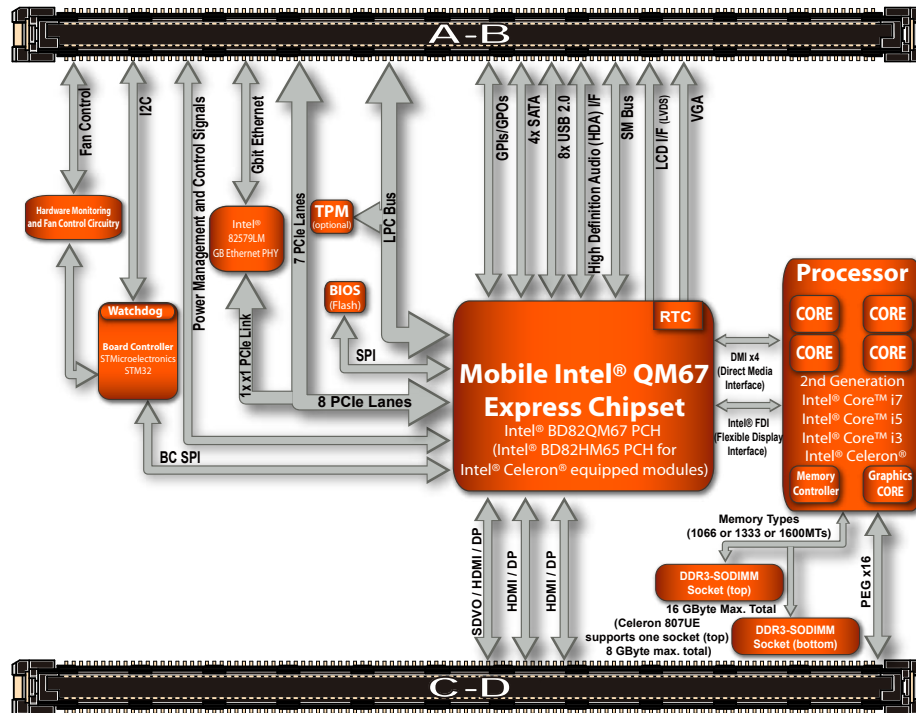


- COM Express Type 6
- Based on 2nd Generation Intel® Core™ low-power processors
- Soldered CPUs for higher shock resistance
- High end graphics performance
- Intel® Turbo Boost Technology 2.0

**COM**  **Express®**

Formfactor	COM Express™ Basic   (95 x 125 mm)   Type 6 Connector Layout																														
CPU	<table border="0"> <tr> <td>Intel® Celeron™ 807UE</td> <td>1x 1.0GHz</td> <td>1MB L3 cache</td> <td>1333MT/s</td> <td>TDP 10 W</td> </tr> <tr> <td>Intel® Celeron™ 827E</td> <td>1x 1.4GHz</td> <td>1.5MB L3 cache</td> <td>1333MT/s</td> <td>TDP 17 W</td> </tr> <tr> <td>Intel® Celeron™ 847E</td> <td>2x 1.1GHz</td> <td>2MB L2 cache</td> <td>1333MT/s</td> <td>TDP 17 W</td> </tr> <tr> <td>Intel® Core™ i3-2340UE</td> <td>2x 1.3GHz</td> <td>3MB L2 cache</td> <td>1333MT/s</td> <td>TDP 17 W</td> </tr> <tr> <td>Intel® Core™ i7-2610UE</td> <td>2x 1.5GHz</td> <td>3MB L2 cache</td> <td>1333MT/s</td> <td>TDP 17 W</td> </tr> <tr> <td>Intel® Core™ i7-2655LE</td> <td>2x 2.2GHz</td> <td>4MB L2 cache</td> <td>1333MT/s</td> <td>TDP 25 W</td> </tr> </table> <p>Intel® Turbo Boost Technology 2.0   Intel® Hyper-Threading Technology   Integrated dual channel memory controller   up to 25.6 GByte/sec. memory bandwidth   Integrated Intel® HD Graphics 3000 with dynamic frequency up to 1.2GHz   Intel® Clear Video HD Technology</p>	Intel® Celeron™ 807UE	1x 1.0GHz	1MB L3 cache	1333MT/s	TDP 10 W	Intel® Celeron™ 827E	1x 1.4GHz	1.5MB L3 cache	1333MT/s	TDP 17 W	Intel® Celeron™ 847E	2x 1.1GHz	2MB L2 cache	1333MT/s	TDP 17 W	Intel® Core™ i3-2340UE	2x 1.3GHz	3MB L2 cache	1333MT/s	TDP 17 W	Intel® Core™ i7-2610UE	2x 1.5GHz	3MB L2 cache	1333MT/s	TDP 17 W	Intel® Core™ i7-2655LE	2x 2.2GHz	4MB L2 cache	1333MT/s	TDP 25 W
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Intel® Core™ i7-2655LE	2x 2.2GHz	4MB L2 cache	1333MT/s	TDP 25 W																											
DRAM	2 Sockets   SO-DIMM DDR3 up to 1600MT/s and 16 GByte																														
Chipset	Mobile Intel® 6 Series Chipset: Intel® QM67 / Intel® HM65 (Intel® Celeron™ version)																														
Ethernet	Intel® 82579 GbE LAN Controller with AMT 7.0 support																														
I/O Interfaces	7x PCI Express™ GEN. 2.0 lanes   1x PEG   2x Serial ATA® with 6 Gb/s   2x Serial ATA® with 3 Gb/s (AHCI) RAID 0/1/5/10 support (QM67 only)   2x ExpressCard®   8x USB 2.0 (EHCI)   LPC bus   I²C bus (fast mode / 400 kHz / multi-master)																														
Sound	Digital High Definition Audio Interface with support for multiple audio codecs																														
Graphics	Intel® Flexible Display Interface (FDI)   OpenGL 3.0 and DirectX10.1 support   Two independent pipelines for full dual view support optional High performance hardware MPEG-2 decoding   WMV9 (VC-1) and H.264 (AVC) support Blu-ray support @ 40 MBit/s   hardware motion compensation																														
LVDS	Dual channel LVDS transmitter   Supports flat panels 2x24 Bit interface   VESA mappings   resolutions up to 1920x1200   Automatic Panel Detection via EDID/EPI																														
Digital Display Interface	1x SDVO / DisplayPort 1.1 / TMDS (DVI / HDMI)   2x DisplayPort 1.1 / TMDS (DVI   HDMI)																														
CRT Interface	350 MHz RAMDAC   resolutions up to QXGA (2048x1536)																														
congatec Board Controller	Multi Stage Watchdog   non-volatile User Data Storage   Manufacturing and Board Information   Board Statistics   BIOS Setup Data Backup I²C bus (fast mode / 400 kHz / multi-master)   Power Loss Control																														
Embedded BIOS Features	AMI Aptio® UEFI 2.x firmware   8 MByte serial SPI firmware flash   High Accessible Program (HAP)																														
Security	The conga-TS67 can be optionally equipped with a discrete "Trusted Platform Module" (TPM). It is capable of calculating efficient hash and RSA algorithms with key lengths up to 2,048 bits and includes a real random number generator. Security sensitive applications such as gaming and e-commerce will benefit also with improved authentication   integrity and confidence levels.																														
Power Management	ACPI 4.0 with battery support																														
Operating Systems	Microsoft® Windows 8   Microsoft® Windows 7   Linux   Microsoft® Windows® embedded Standard																														
Power Consumption	Typ. application: tbd.   see manual for full details   CMOS Battery Backup																														
Temperature	Operating: 0 .. +60°C   Storage: -20 .. +80°C																														
Humidity	Operating: 10 - 90% r. H. non cond.   Storage: 5 - 95% r. H. non cond.																														
Size	95 x 125 mm (3.74" x 4.92")																														

# conga-TS67 | Block diagram



# conga-TS67 | Order Information

Article	PN	Description
conga-TS67/i7-2655LE	046401	Intel® Core™ i7-2655LE dual core processor with 2.2GHz   4MB L3 cache and 1333MT/s dual channel DDR3 memory interface
conga-TS67/i7-2610UE	046402	Intel® Core™ i7-2610UE dual core processor with 1.5GHz   3MB L3 cache and 1333MT/s dual channel DDR3 memory interface
conga-TS67/i3-2340UE	046403	Intel® Core™ i3-2340UE dual core processor with 1.3GHz   3MB L3 cache and 1333MT/s dual channel DDR3 memory interface
conga-TS67/847E	046404	Intel® Celeron® 847E dual core processor with 1.1GHz   2MB L3 cache and 1333MT/s dual channel DDR3 memory interface
conga-TS67/827E	046405	Intel® Celeron® 827E single core processor with 1.4GHz   1.5MB L3 cache and 1333MT/s dual channel DDR3 memory interface
conga-TS67/807UE	046406	Intel® Celeron® 807UE single core processor with 1.0GHz   1MB L3 cache   1333MT/s single channel DDR3 memory interface and no PEG Port
conga-TS67/HSP-HP-B	046450	Standard heatspreader for high performance COM Express modules conga-TS67 and TS77 with integrated heat pipes. All standoff are with 2.7mm bore hole
conga-TS67/HSP-HP-T	046451	Standard heatspreader for high performance COM Express modules conga-TS67 and TS77 with integrated heat pipes. All standoff are M2.5mm thread
conga-TS67/CSP-HP-B	046452	Standard passive cooling solution for high performance COM Express modules conga-TS67 and TS77 with integrated heat pipes 15mm silver fins and 20mm overall heat sink height. All standoff are with 2.7mm bore hole
conga-TS67/CSP-HP-T	046453	Standard passive cooling solution for high performance COM Express modules conga-TS67 and TS77 with integrated heat pipes 15mm silver fins and 20mm overall heat sink height. All standoff are M2.5mm thread
conga-TS67/CSA-HP-B	046454	Standard active cooling solution for high performance COM Express modules conga-TS67 and TS77 with integrated heat pipes   15mm silver fins   20mm overall heat sink height and integrated 12V fan. All standoff are with 2.7mm bore hole
conga-TS67/CSA-HP-T	046455	Standard active cooling solution for high performance COM Express modules conga-TS67 and TS77 with integrated heat pipes   15mm silver fins   20mm overall heat sink height and integrated 12V fan. All standoff are M2.5mm thread
DDR3L-SODIMM-1600 (2GB)	068755	DDR3L SODIMM memory module with 1600 MT/s (PC3L-12800S) and 2GB RAM
DDR3L-SODIMM-1600 (4GB)	068756	DDR3L SODIMM memory module with 1600 MT/s (PC3L-12800S) and 4GB RAM
DDR3L-SODIMM-1600 (8GB)	068757	DDR3L SODIMM memory module with 1600 MT/s (PC3L-12800S) and 8GB RAM

## Accessories

conga-TEVAL	065800	Evaluation carrier board for Type 6 COM-Express-modules
conga-LDVI/EPI	011115	LVDS to DVI converter board for digital flat panels with onboard EEPROM
COM-Express-carrier-board-Socket-5	400007	Connector for COM-Express carrier boards   height 5mm   packing unit 4 pieces
COM-Express-carrier-board-Socket-8	400004	Connector for COM-Express carrier boards   height 8mm   packing unit 4 pieces

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